

Mek SpectorBOX X1

Modular Full 3D AOI System For THT Solder Joints And THT Components



Benefits

→ Full 3D Measurement Optimized For THT Solder Joints Post Wave And Selective Soldering

Volumetric data for detection of soldering defects, pin height measurement, annular ring coverage and detection of "blow" holes

- → Full 3D Measurement Including THT Components Capability to measure and inspect also the THT components
- → Max. PCB Size 550mm x 550mm (21.7" x 21.7") Large PCB sizes or pallets are supported. The optics move in X,Y and Z directions to cover the inspection area
- High Clearance Between PCB Surface And The Optics

200mm (7.9") THT components side and 100mm (3.9") THT solder side clearance for a no exceptions inspection

- → Compatible With Mek Catch System For MES Gateways, Repair, Real Time Monitoring And SPC Catch System is compatible with Windows 11 and is a complete suite for data collection, display and statistics
- Reflection Free Measurement
 Colour and glare optimized. Unwanted reflections from shiny surfaces are removed

- High Speed Measurement
 Using modern processor and storage power for parallel imaging, calculation and data transmission
- Windows® 11 Based Software
 Ensuring high security data protection, demanded by modern IT departments
- → Large Field Of View (FoV) 60mm x 60mm (2.4" x 2.4") FoV ensures measurement of larger objects and high speed inspection
- → Z-Axis Moving Optical Unit Focus and position optimally for variying PCB and component distances or warpage
- → Compatible With Mek EZPro EZPro is the software tool developed by Mek for ultra fast automatic programming of full measurement recipes
- → Modular Inspection Possibilities: Bottom, Top Or Dual Possibility to combine 2 SpectorBOX X systems for simultaneous dual sided measurement
- → Simple Compatibility With Integrators 3rd party turn-key solutions readily available. SpectorBOX X systems fit conviniently inside main frames







Specifications SpectorBOX X1 550

Characteristics	
Product Type	Full 3D THT AOI
Application	Top Side, Bottom Side , Dual Side
Camera Movement	X,Y and Z
PCB Movement	Stationary
Parts Inspection	Solder Volume, THT Pin Height, Components Height, Coplanarity, Presence, polarity, Shape, Offset, Text
Image Processing	3D Volume Measurement, Spectral Histogram Analysis, Custom Algorithms
Camera/Lens Type	CMOS Camera with High Resolution Lens
Lighting System	3D Dedicated Lighting, RGB LED's
System Specifications	
Camera Resolution	10Мр
Lens Resolution	19µm
XYZ Repeatability	1μm
Top Clearance (Top-Down Application)	200mm (7.9")
Bot Clearance (Bottom-Up Application)	100mm (3.9")
Max. PCB Size	550mm x 550mm (21.7" x 21.7")
Z-Axis Stroke	60mm (2.4")
Inspection Speed Typical	0.6 sec per FoV
Electrical Requirements	200-240 VAC /1000W
Interfacing	
Control PC Type	Windows® 11 Pro
Data Interface	Ethernet
Repair/Monitor/SPC System/MES-interface	CSV Centroid File (Placement File)
Repair/Monitor/SPC System/MES-interface	Mek Catch System (Windows 7/8/10/11) (Option)
3rd Party Interfacing (MES) & Data Storage	Enterprise SQL DB/XML Files/Socket (Catch System Option)
General	
Operating Temperature	15-30 deg. C(60-90 deg. F)
Operating Humidity	15-80 % RH
External Size Main Unit	W1203 x D1203 x H426 mm (47.4" x 47.4" x 16.8")
External Size Control Unit	W600 x D259 x H400mm (23.6" x 10.2" x 15.8")
Weight	160kg (353lbs)



Mek Americas LLC

8275 S Eastern Ave, suite 200 Las Vegas, NV 89123 T+1 702 660 6112 info@marantz-electronics.com www.marantz-electronics.com

Marantz Electronics Ltd.

4F North Square I, Yokohama Business Park, 134 Goudo-cho, Hodogayaku, Yokohama, Kanagawa Japan 240-0005 T+81-45-340-5566 info@marantz-mek.co.jp, www.model22x.com

Mek Europe BV

Polluxstraat 2b 5047 RB Tilburg, Netherlands T +31 40 7114111 info@mek-europe.com www.mek-europe.com





because inspection matters